C1 Cont'd

pairs of interconnected terminals disposed closely adjacent the corresponding lead and projecting outwardly therefrom each have a reduced dimension such that a maximum distance is maintained between laterally adjacent pairs of roots of individual lead frames.

Please add Claims 17-21 as follows:

17. (New) The frame of Claim 3 wherein each said terminal root defines therein a pair of said hollows on opposite sides thereof.

18. (New) The frame of Claim 3 wherein each said terminal root defines therein a said hollow, said hollow comprising an area of reduced thickness as defined between front and rear sides of said frame.

19. (New) The frame of Claim 4 wherein said reduced dimensions of the respective roots each comprise a root width as defined between opposite sides of the respective root.

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20. (New) The frame of Claim 4 wherein said reduced dimensions of the respective roots each comprise a root thickness as defined between front and rear sides of said frame.

21. (New) A frame for forming individual semiconductor packages, said frame comprising a plurality of lead frames arranged in a matrix and semiconductor devices respectively mounted on die pads supported on the individual lead frames by suspending leads, each said lead frame having a metal lead which defines a boundary between said lead frame and an adjacent said lead frame, and pairs of terminals project in opposite directions from each said lead disposed between an adjacent pair of lead frames, each said terminal having a root defining a recessed area therein and being disposed closely adjacent and projecting from the corresponding said lead.